

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10807417
<b>Filing Date:</b>	23-Mar-2004
<b>Title of Invention:</b>	Microcap wafer bonding apparatus
<b>First Named Inventor/Applicant Name:</b>	R. Shane Fazzio
<b>Filer:</b>	Thomas F. Woods
<b>Attorney Docket Number:</b>	10030899-1

Filed as Large Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

Filing a brief in support of an appeal	1402	1	540	540
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**Post-Allowance-and-Post-Issuance:**

<b>Extension-of-Time:</b>	
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>540</b>